



DEFENSE LOGISTICS AGENCY
DLA LAND AND MARITIME
POST OFFICE BOX 3990
COLUMBUS, OH 43218-3990

IN REPLY
REFER TO

DSCC-VQ (VQC-10-019894/Mr. Granchi/614-692-9975/dg)

December 15, 2010

SUBJECT: Laboratory Suitability for MIL-STD-883, FSC 5962

Mr. Glenn Frashure
Vice President, Quality and Reliability Assurance
Micross Components
8701 Cross Park Drive
Austin, TX 78754-4566

Dear Mr. Frashure:

Micross Components, formerly Austin Semiconductor Inc. (ASI), has demonstrated to the Defense Supply Center, Columbus (DSCC), compliance with MIL-STD-883, the test standard for integrated circuits. This letter is revised to reflect the recent name change of Austin Semiconductor Inc. to Micross Components. The current status of Micross' Laboratory Suitability, test methods and conditions, are shown on the enclosure. All testing must be performed in accordance with MIL-PRF-38535 and MIL-STD-883 test methods.

Effective immediately, the previous Lab Suitability letter, DSCC-VQC-09-018810, issued to ASI by DSCC, is superseded by this letter. This Laboratory Suitability is subject to the conditions in DoD 4120.24 M, Defense Standardization Program.

Micross Components and QPL/QML test labs shall notify the qualifying activity immediately after learning of a potential issuance of a GIDEP alert, problem advisory or major quality/reliability problem on their QPL/QML products utilizing test methods listed on the enclosure. Failure to provide prior notification may be grounds for removal from QML-38535.

This Lab Suitability is valid until terminated by written notice from DSCC. If warranted, it may be withdrawn by DSCC at any time. Each of these facilities is subject to an audit by DSCC with minimum notice.

Sincerely,

MICHAEL S. ADAMS
Chief
Custom Devices Branch

cc:
DSCC (Michael Grammens)
DSCC (Scott Thomas)
DSCC (Alberta Pertuskevich)

Enclosure to VQC-10-019894

TEST	METHOD/ CONDITIONS	Micross	Millenium Microtech	Atlantic Analytical & Oneida	Hi-Rel Labs	Microtech Labs	Hi-Reliabilty Microelectronics
Moisture Resistance	1004	X	X				
Steady State Life Test	1005/A-E	X	X				
Stabilization Bake	1008	X					
Salt Atmosphere	1009/A-D	X	X				
Temperature Cycling	1010/A-F	X	X				
Thermal Shock	1011/B,C	X	X				
Seal	1014/A1,A2,B,C	Helium	Krypton				
Burn-in	1015/A-E	X	X				
Internal Water Vapor Cont.	1018			X			
Constant Acceleration	2001/A-E	X	X				
Mechanical Shock	2002/B	X	X				
Solderability	2003	X	X				
Lead Integrity	2004/B1,B2,D	X	X				
Vibration, Variable Freq.	2007/A	X	X				
External Visual	2009	X	X				
Internal Visual	2010/A,B	X	X				
Bond Strength	2011/C,D	X	X				
Radiography	2012	X					
Resistance to Solvents	2015	X	X				
Physical Dimensions	2016	X	X				
SEM	2018				X	X	
Die Shear Strength	2019 & 2027	X	X				
PIND	2020/A,B	X	X		X		
Nondestructive Bond Pull	2023	X	X				
Lid Torque	2024	X					
Adhesion of Lead Finish	2025	X					
Substrate Attach Strength	2027	X	X				
Pin Grid Package Destructive Lead Pull Test	2028	X					
Ultrasonic Die Attach Insp.	2030	X					
ESDS	3015						X
Electrical Test	Paragraph 4.5	X	X				